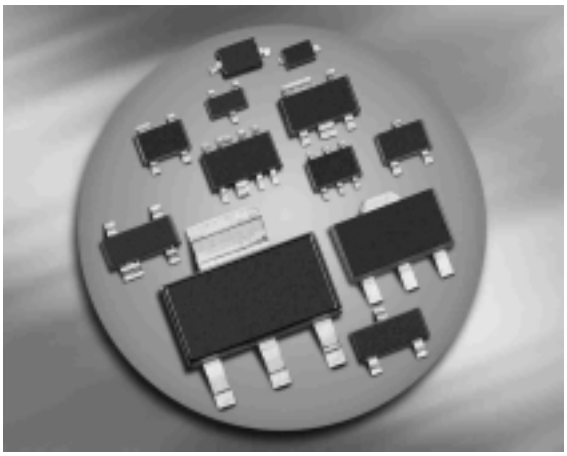
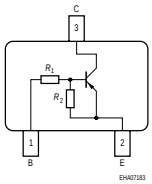
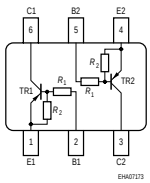
PNP Silicon Digital Transistor

- Switching circuit, inverter, interface circuit, driver circuit
- Built in bias resistor (R_1 = 10 kΩ , R_2 = 10 kΩ)
- BCR183S / U: Two internally isolated transistors with good matching in one multichip package
- BCR183S / U: For orientation in reel see package information below



BCR183/F/L3 **BCR183S/U**
BCR183T/W





Type	Marking	Pin Configuration						Package
BCR183	WMs	1=B	2=E	3=C	-	-	-	SOT23
BCR183F	WMs	1=B	2=E	3=C	-	-	-	TSFP-3
BCR183L3	WM	1=B	2=E	3=C	-	-	-	TSLP-3-4
BCR183S	WMs	1=E1	2=B1	3=C2	4=E2	5=B2	6=C1	SOT363
BCR183T	WM	1=B	2=E	3=C	-	-	-	SC75
BCR183U	WMs	1=E1	2=B1	3=C2	4=E2	5=B2	6=C1	SC74
BCR183W	WMs	1=B	2=E	3=C	-	-	-	SOT323

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	50	V
Collector-base voltage	V_{CBO}	50	
Input forward voltage	$V_{i(fwd)}$	40	
Input reverse voltage	$V_{i(rev)}$	10	
Collector current	I_C	100	mA
Total power dissipation-	P_{tot}		mW
BCR183, $T_S \leq 102°C$		200	
BCR183F, $T_S \leq 128°C$		250	
BCR183L3, $T_S \leq 135°C$		250	
BCR183S, $T_S \leq 115°C$		250	
BCR183T, $T_S \leq 109C$		250	
BCR183U, $T_S \leq 118°C$		250	
BCR183W, $T_S \leq 124°C$		250	
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point[1)]	R_{thJS}		K/W
BCR183		≤ 240	
BCR183F		≤ 90	
BCR183L3		≤ 60	
BCR183S		≤ 140	
BCR183T		≤ 165	
BCR183U		≤ 133	
BCR183W		≤ 105	

[1]For calculation of R_{thJA} please refer to Application Note Thermal Resistance

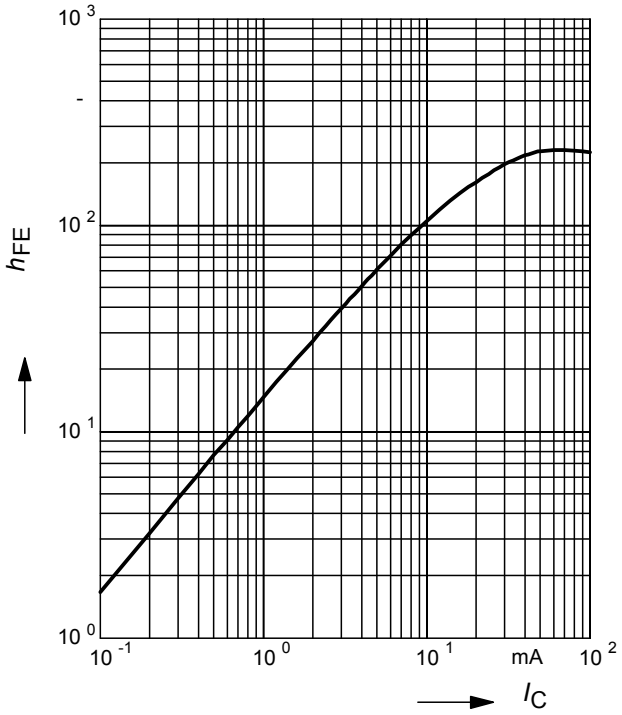
Electrical Characteristics at T_A = 25°C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage I_C = 100 µA, I_B = 0	$V_{(BR)CEO}$	50	-	-	V
Collector-base breakdown voltage I_C = 10 µA, I_E = 0	$V_{(BR)CBO}$	50	-	-	
Collector-base cutoff current V_{CB} = 40 V, I_E = 0	I_{CBO}	-	-	100	nA
Emitter-base cutoff current V_{EB} = 10 V, I_C = 0	I_{EBO}	-	-	0.75	mA
DC current gain[1)] I_C = 5 mA, V_{CE} = 5 V	h_{FE}	30	-	-	-
Collector-emitter saturation voltage[1)] I_C = 10 mA, I_B = 0.5 mA	V_{CEsat}	-	-	0.3	V
Input off voltage I_C = 100 µA, V_{CE} = 5 V	$V_{i(off)}$	0.8	-	1.8	
Input on voltage I_C = 2 mA, V_{CE} = 0.3 V	$V_{i(on)}$	1	-	2.5	
Input resistor	R_1	7	10	13	kΩ
Resistor ratio	R_1/R_2	0.9	1	1.1	-
AC Characteristics					
Transition frequency I_C = 10 mA, V_{CE} = 5 V, f = 100 MHz	f_T	-	200	-	MHz
Collector-base capacitance V_{CB} = 10 V, f = 1 MHz	C_{cb}	-	3	-	pF

[1]Pulse test: t < 300µs; D < 2%

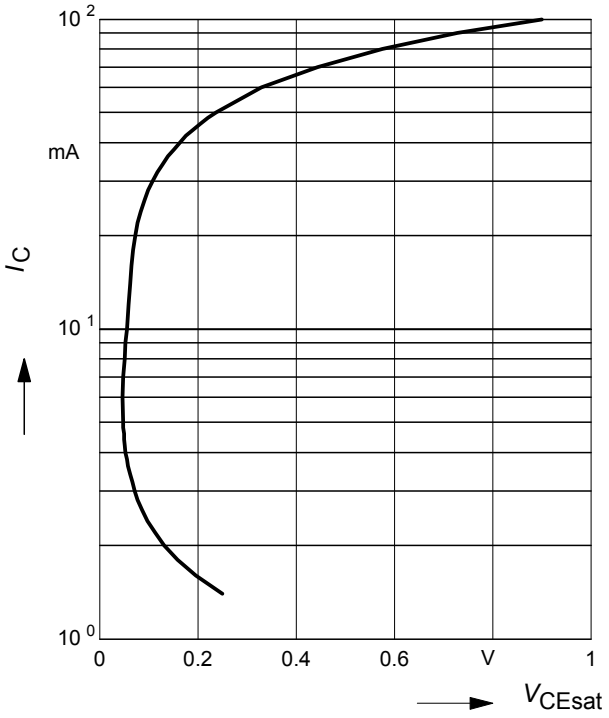
DC current gain $h_{FE} = f(I_C)$

V_{CE} = 5 V (common emitter configuration)



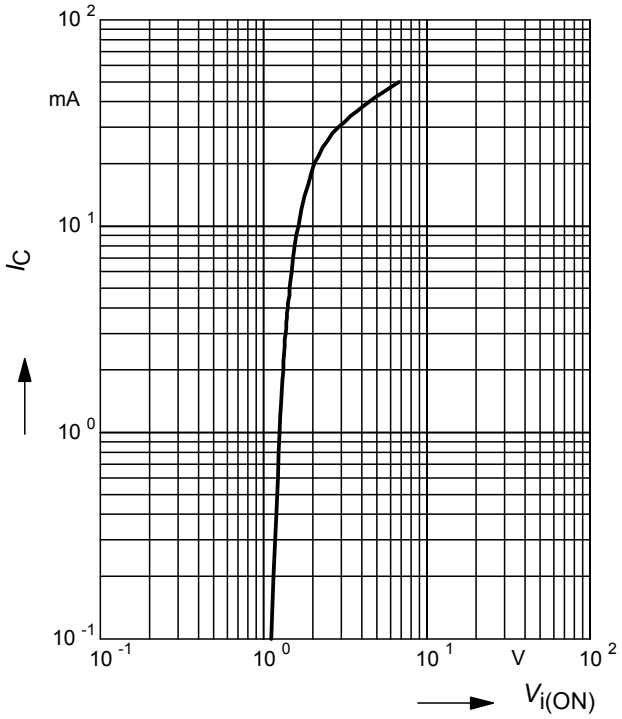
Collector-emitter saturation voltage

$V_{CEsat} = f(I_C)$, h_{FE} = 20



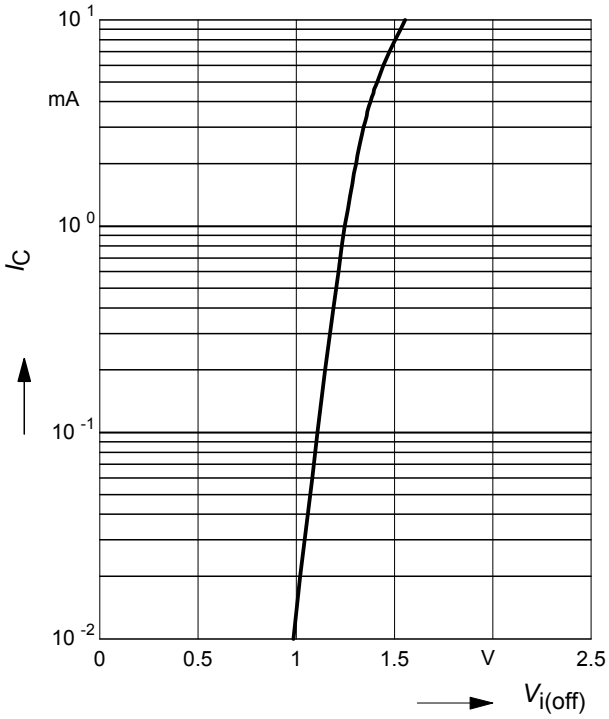
Input on Voltage $V_{i(on)} = f(I_C)$

V_{CE} = 0.3V (common emitter configuration)

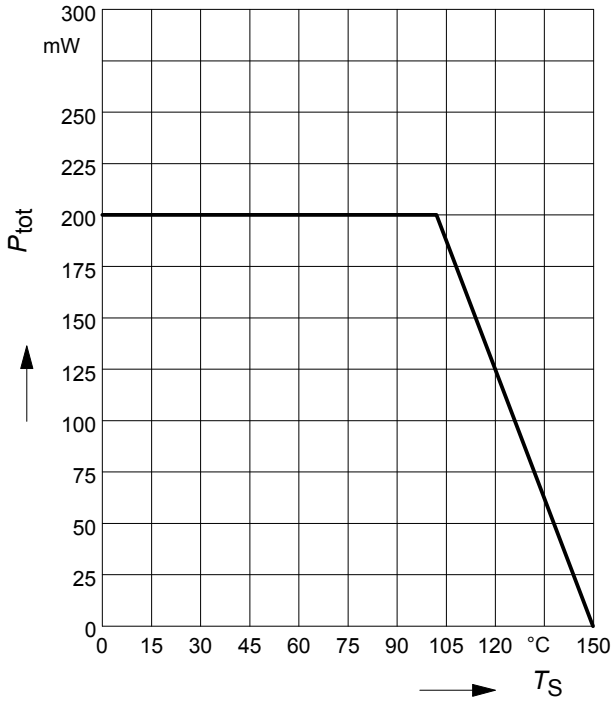


Input off voltage $V_{i(off)} = f(I_C)$

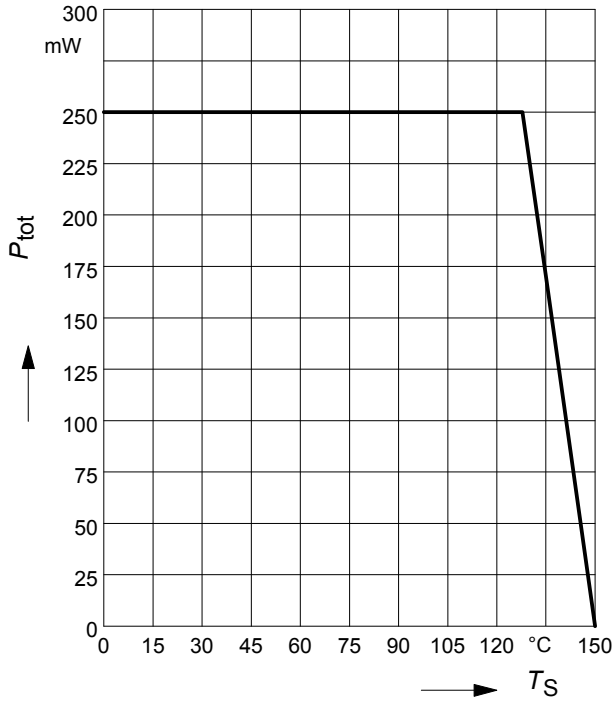
V_{CE} = 5V (common emitter configuration)



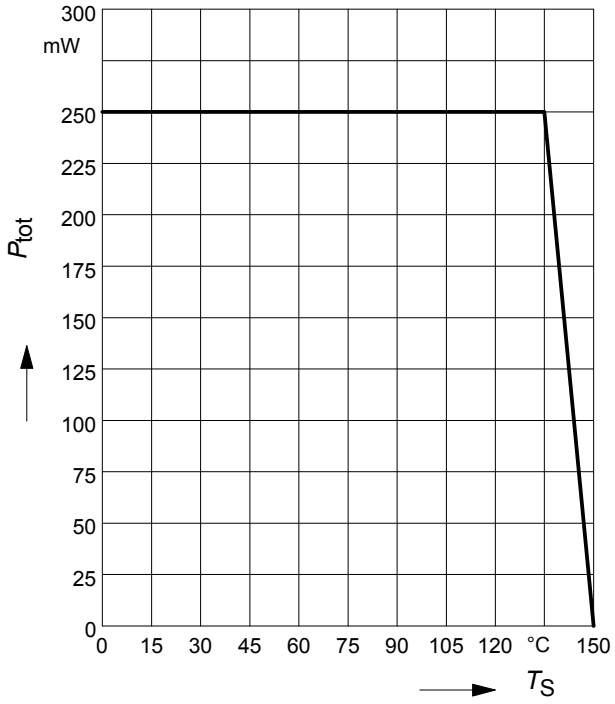
Total power dissipation $P_{tot} = f(T_S)$
BCR183



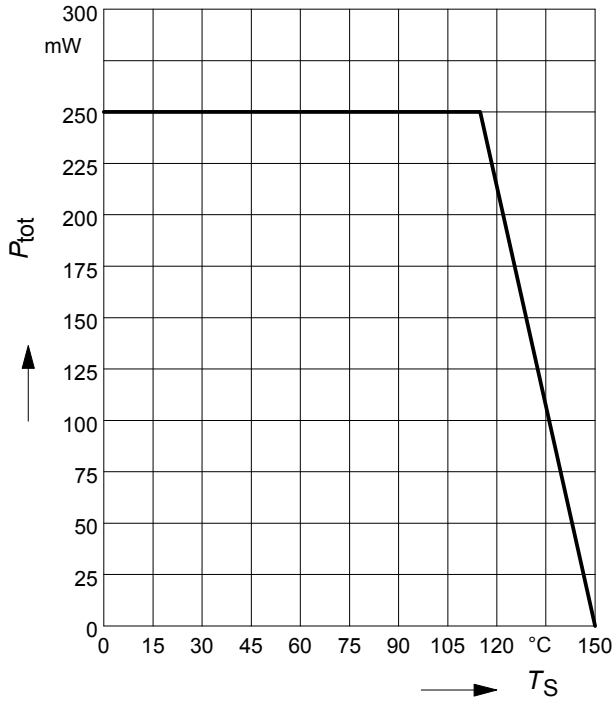
Total power dissipation $P_{tot} = f(T_S)$
BCR183F



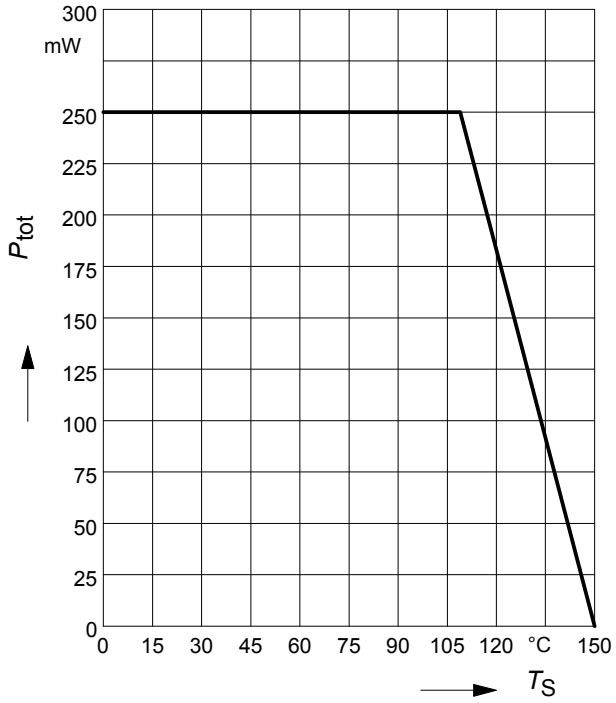
Total power dissipation $P_{tot} = f(T_S)$
BCR183L3



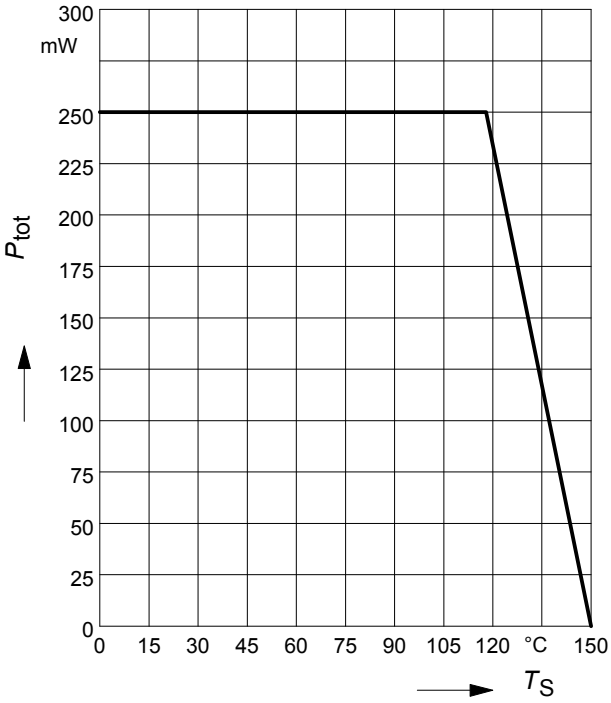
Total power dissipation $P_{tot} = f(T_S)$
BCR183S



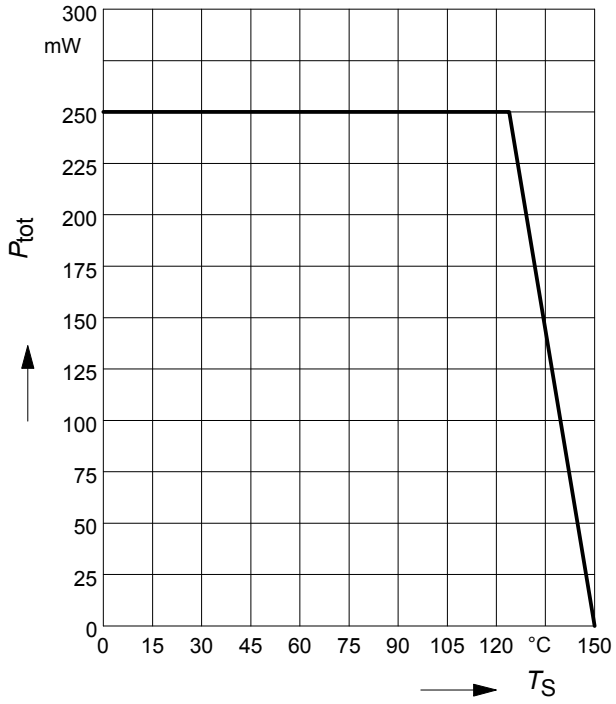
Total power dissipation $P_{tot} = f(T_S)$
BCR183T



Total power dissipation $P_{tot} = f(T_S)$
BCR183U

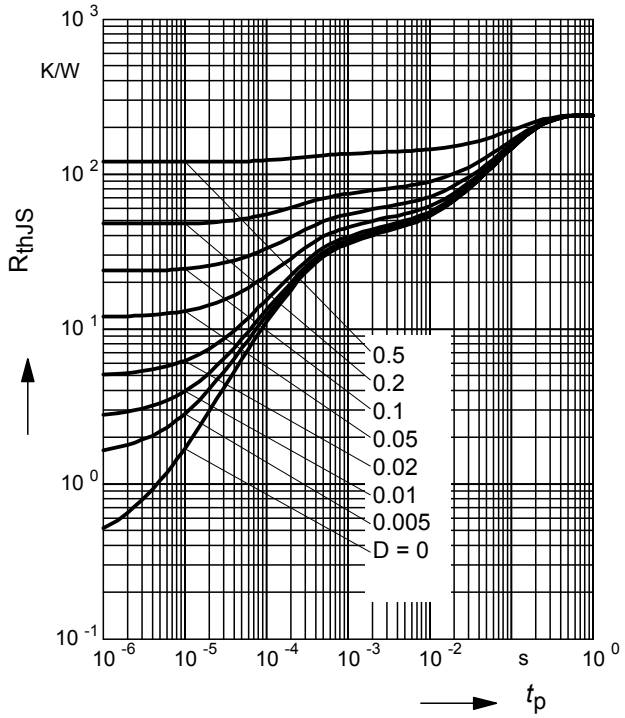


Total power dissipation $P_{tot} = f(T_S)$
BCR183W



Permissible Pulse Load $R_{thJS} = f(t_p)$

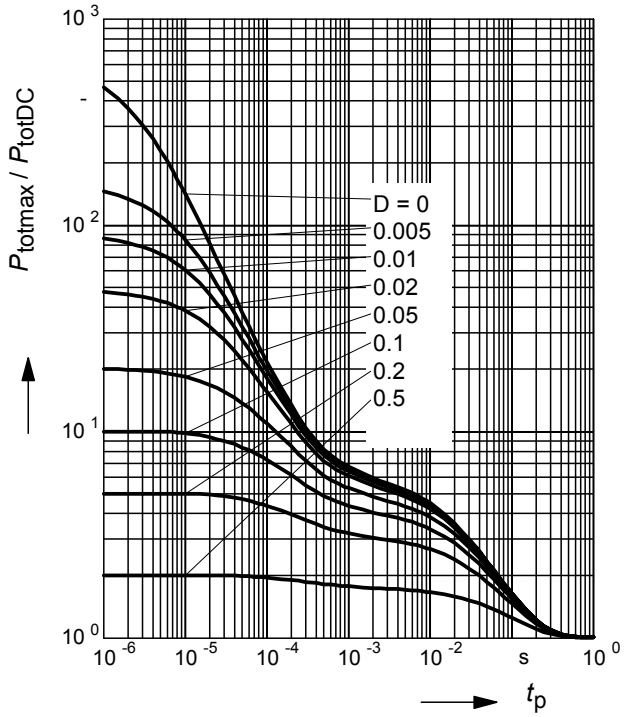
BCR183



Permissible Pulse Load

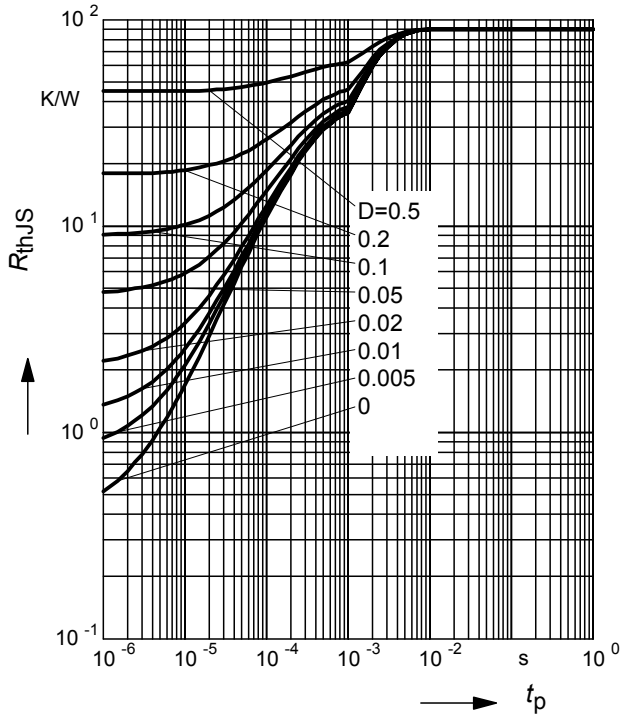
$P_{totmax}/P_{totDC} = f(t_p)$

BCR183



Permissible Puls Load $R_{thJS} = f(t_p)$

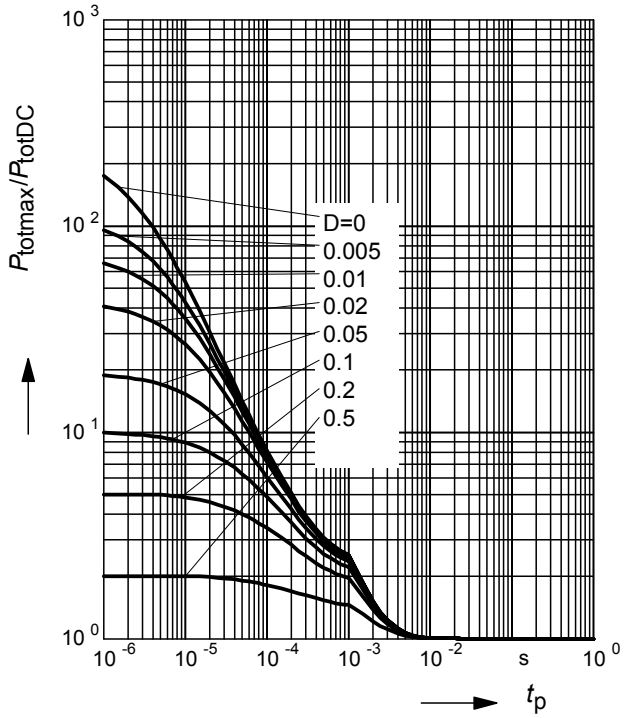
BCR183F



Permissible Pulse Load

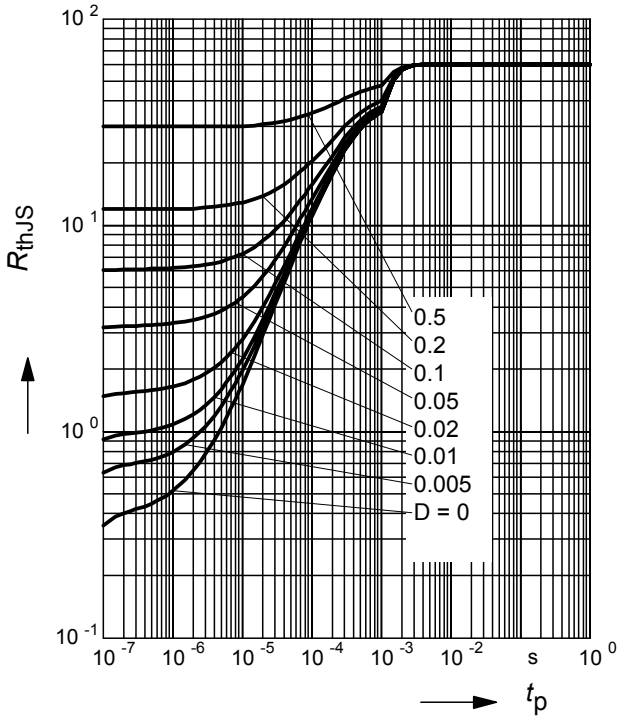
$P_{totmax}/P_{totDC} = f(t_p)$

BCR183F



Permissible Puls Load $R_{thJS} = f(t_p)$

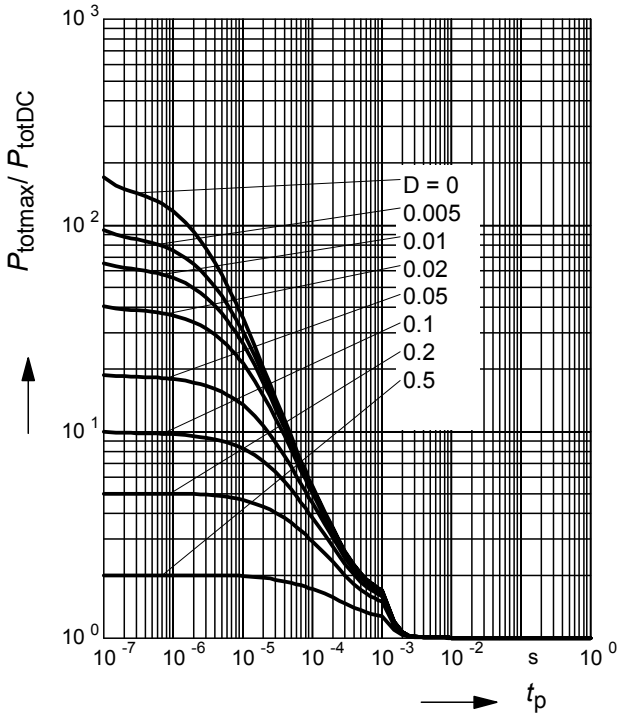
BCR183L3



Permissible Pulse Load

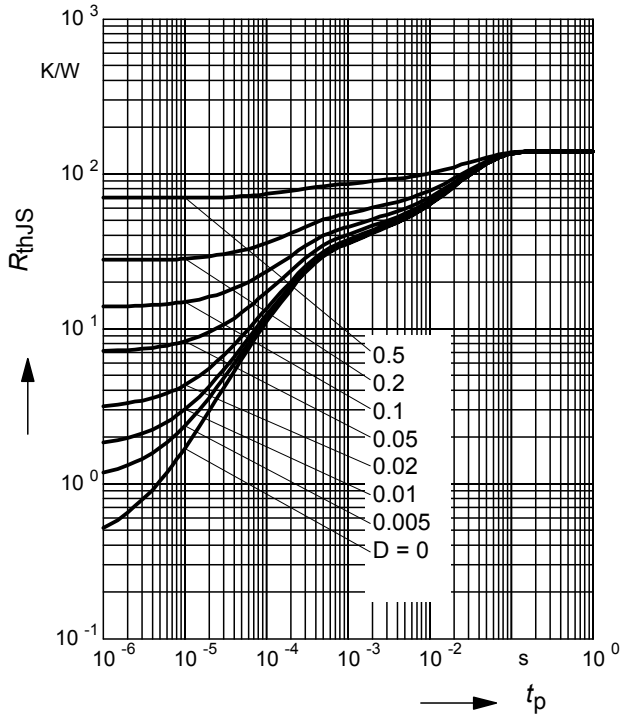
$P_{totmax}/P_{totDC} = f(t_p)$

BCR183L3



Permissible Puls Load $R_{thJS} = f(t_p)$

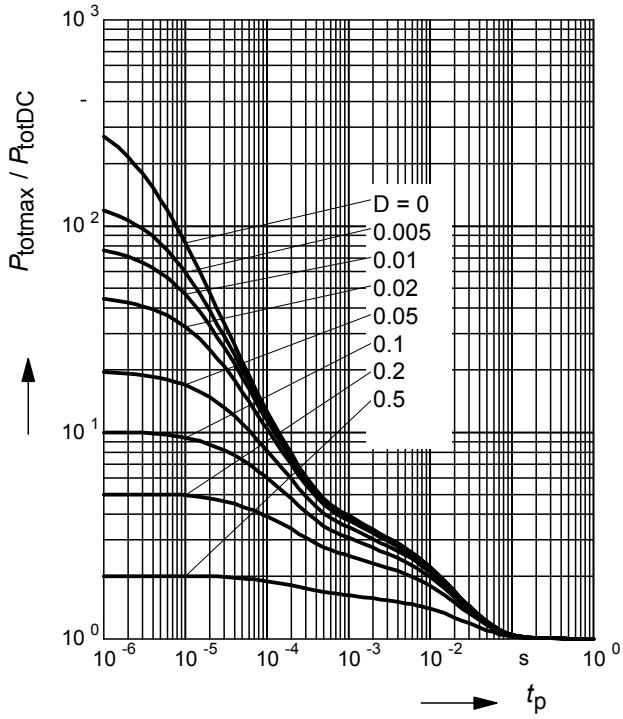
BCR183S



Permissible Pulse Load

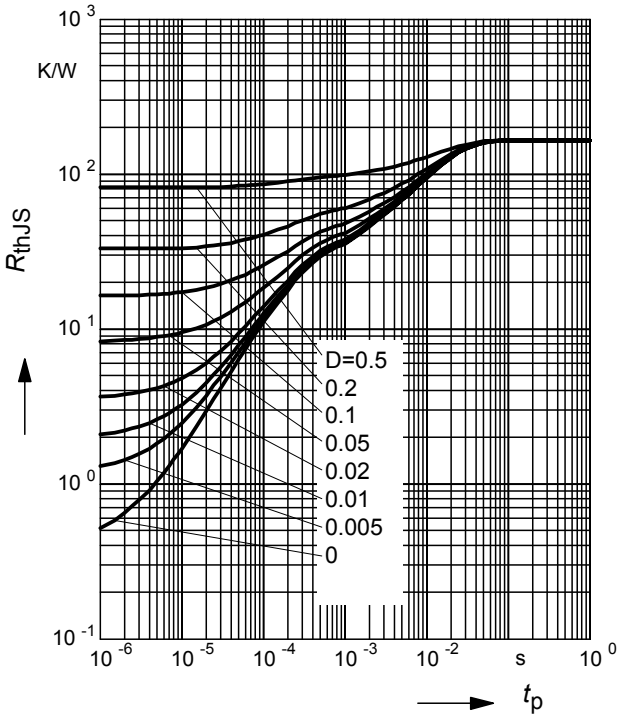
$P_{totmax}/P_{totDC} = f(t_p)$

BCR183S



Permissible Puls Load $R_{thJS} = f(t_p)$

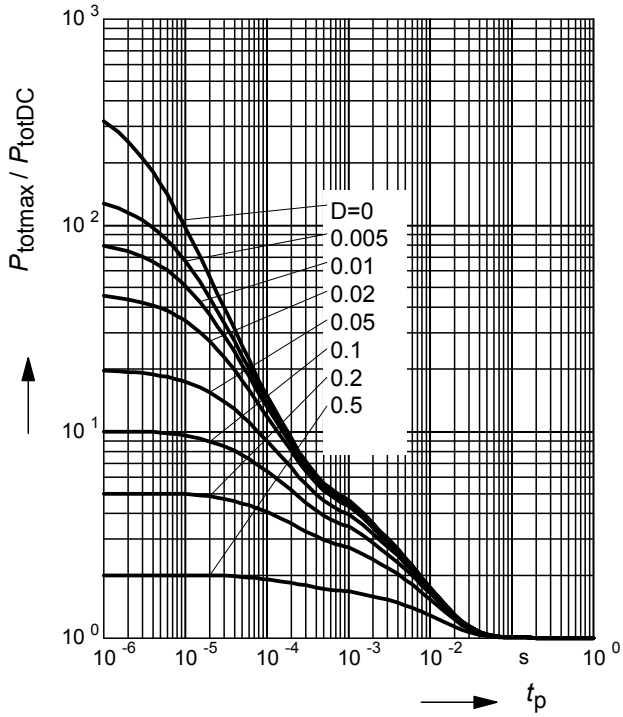
BCR183T



Permissible Pulse Load

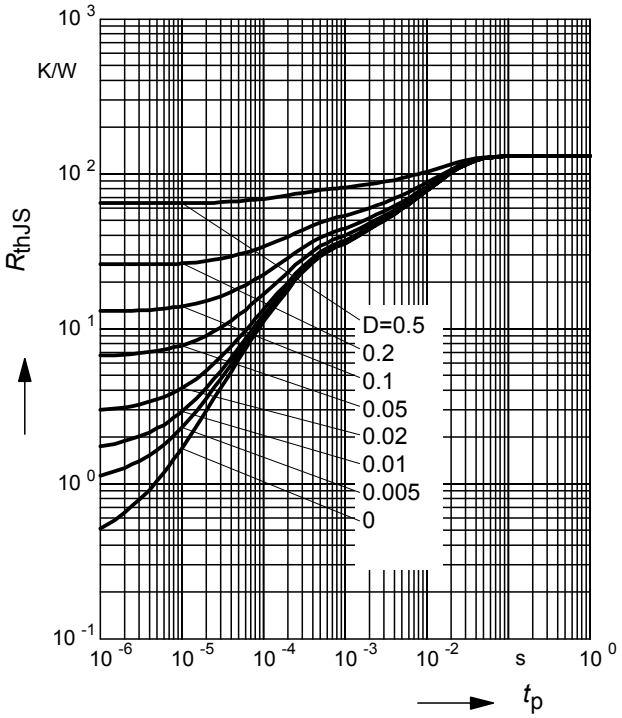
$P_{totmax}/P_{totDC} = f(t_p)$

BCR183T



Permissible Puls Load $R_{thJS} = f(t_p)$

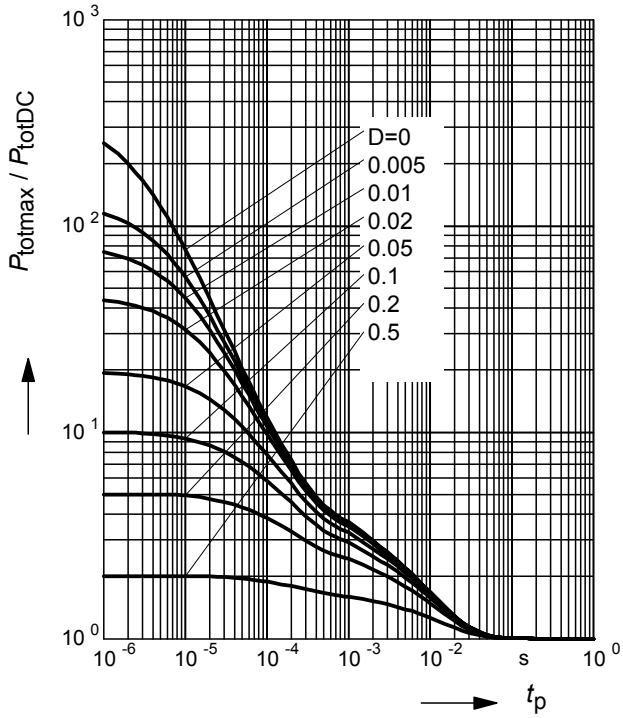
BCR183U



Permissible Pulse Load

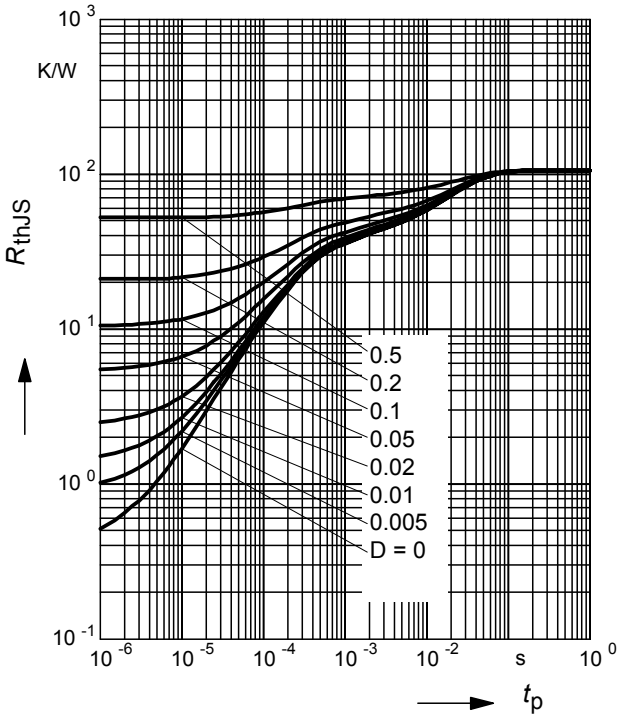
$P_{totmax}/P_{totDC} = f(t_p)$

BCR185U



Permissible Puls Load $R_{thJS} = f(t_p)$

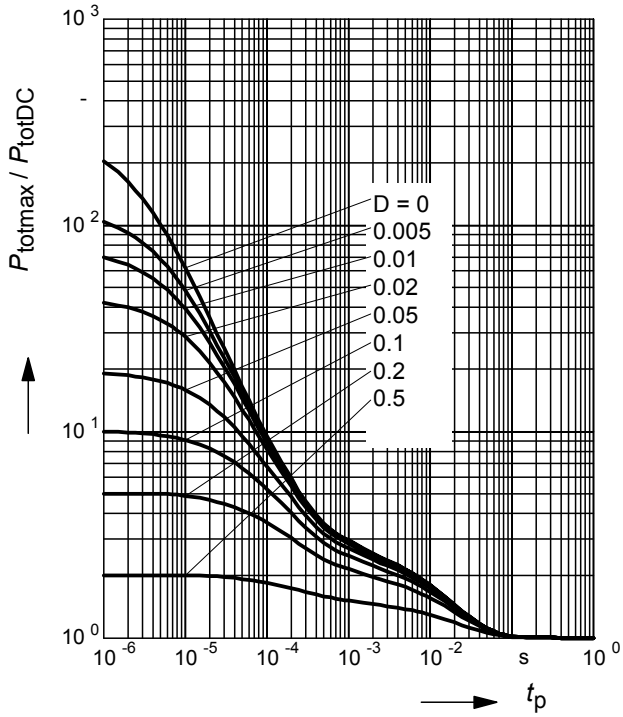
BCR183W



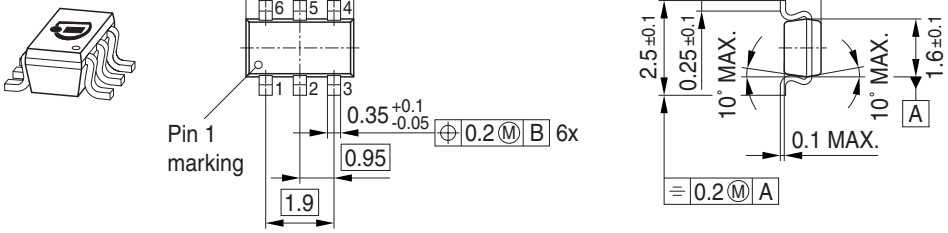
Permissible Pulse Load

$P_{totmax}/P_{totDC} = f(t_p)$

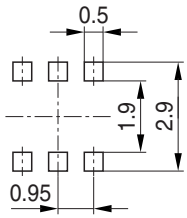
BCR183W



Package Outline

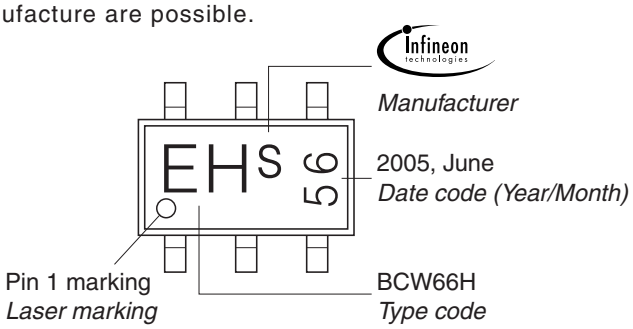


Foot Print



Marking Layout (Example)

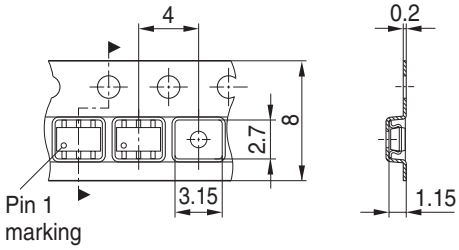
Small variations in positioning of
Date code, Type code and Manufacture are possible.



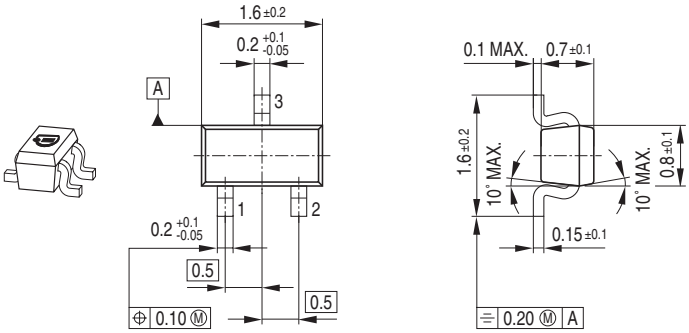
Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel

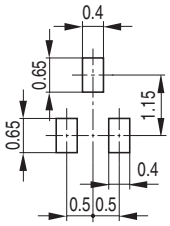
For symmetric types no defined Pin 1 orientation in reel.



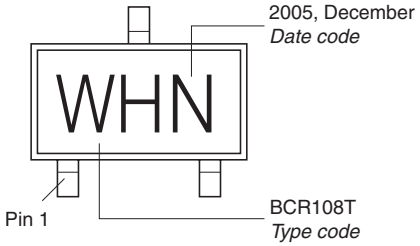
Package Outline



Foot Print

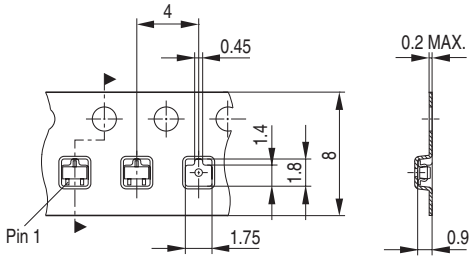


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel

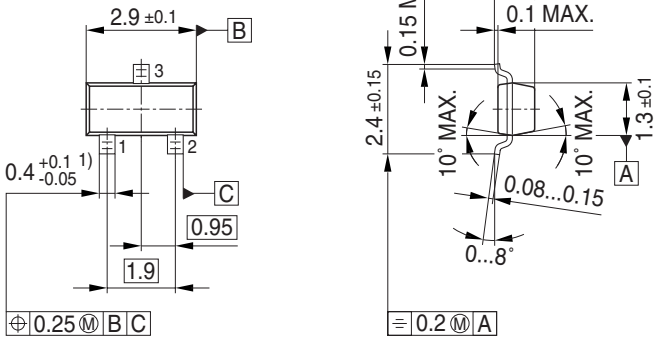


Date Code marking for discrete packages with one digit (SCD80, SC79, SC75[1]) CES-Code

Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	a	p	A	P	a	p	A	P	a	p	A	P
02	b	q	B	Q	b	q	B	Q	b	q	B	Q
03	c	r	C	R	c	r	C	R	c	r	C	R
04	d	s	D	S	d	s	D	S	d	s	D	S
05	e	t	E	T	e	t	E	T	e	t	E	T
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	v	G	V	g	v	G	V	g	v	G	V
08	h	x	H	X	h	x	H	X	h	x	H	X
09	j	y	J	Y	j	y	J	Y	j	y	J	Y
10	k	z	K	Z	k	z	K	Z	k	z	K	Z
11	l	2	L	4	l	2	L	4	l	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

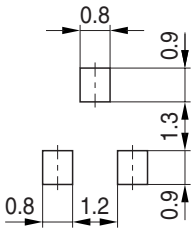
1) New Marking Layout for SC75, implemented at October 2005.

Package Outline

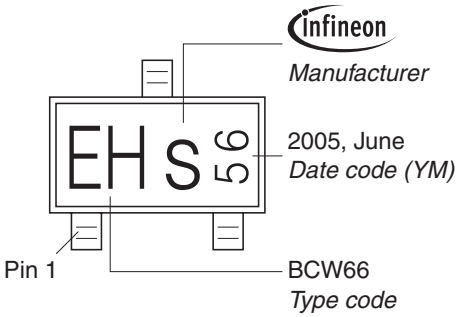


1) Lead width can be 0.6 max. in dambar area

Foot Print

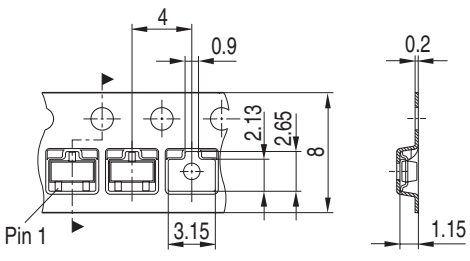


Marking Layout (Example)

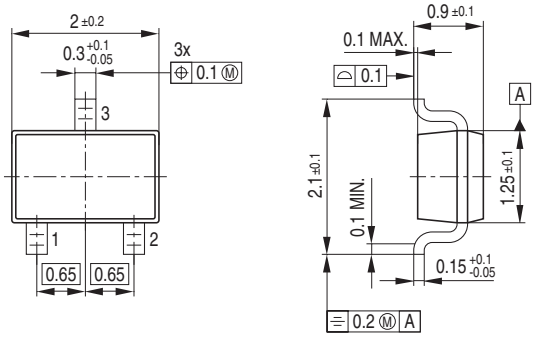


Standard Packing

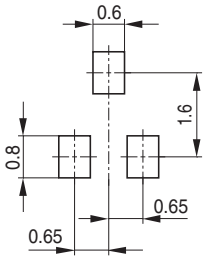
Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



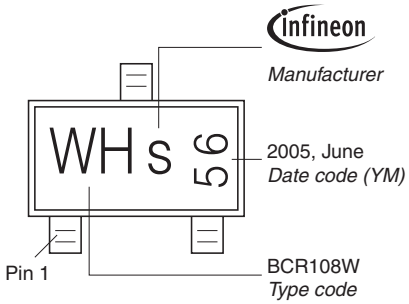
Package Outline



Foot Print

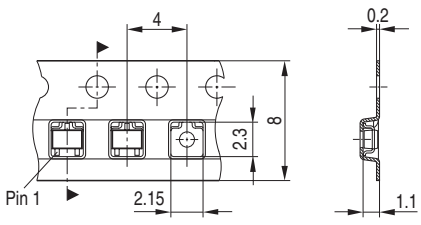


Marking Layout (Example)

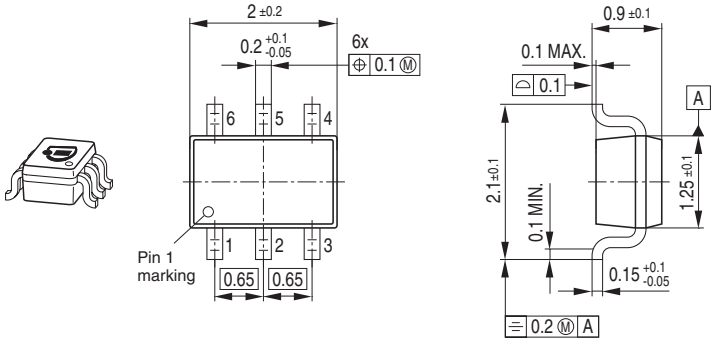


Standard Packing

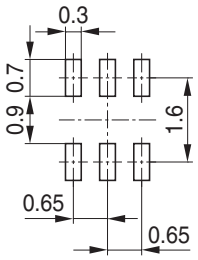
Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



Package Outline

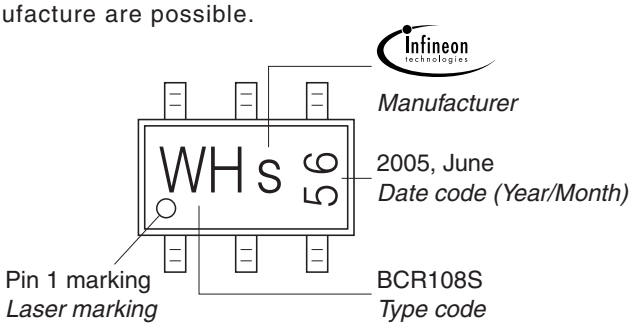


Foot Print



Marking Layout (Example)

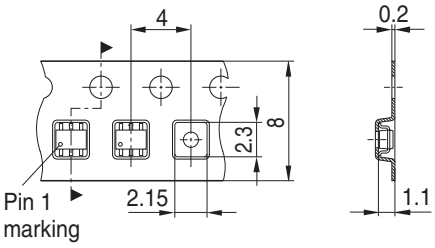
Small variations in positioning of
Date code, Type code and Manufacture are possible.



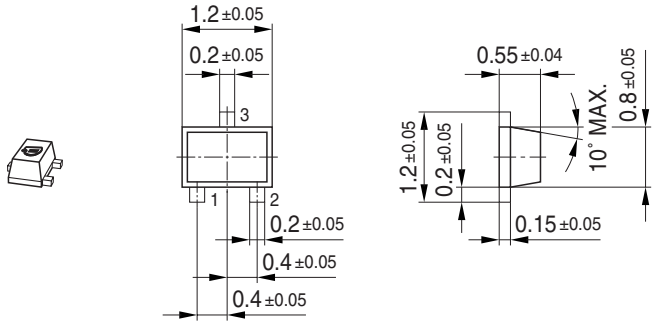
Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel

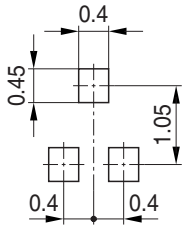
For symmetric types no defined Pin 1 orientation in reel.



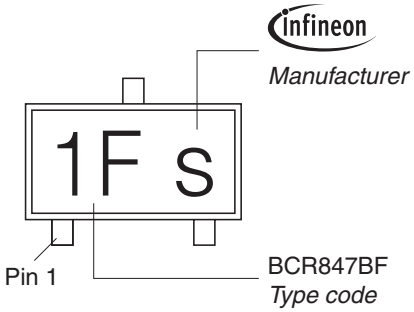
Package Outline



Foot Print

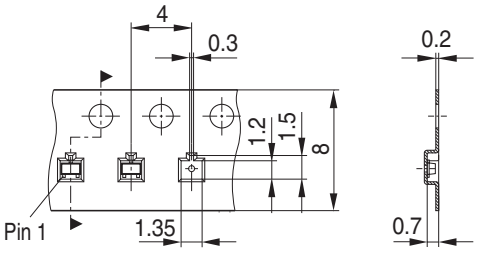


Marking Layout (Example)

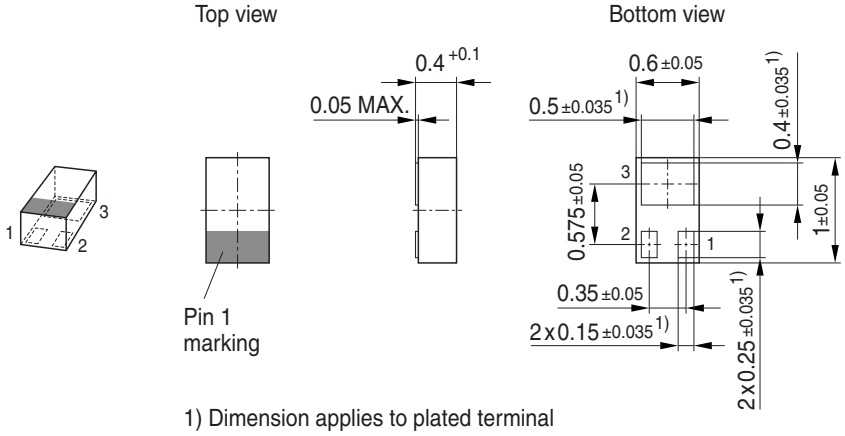


Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



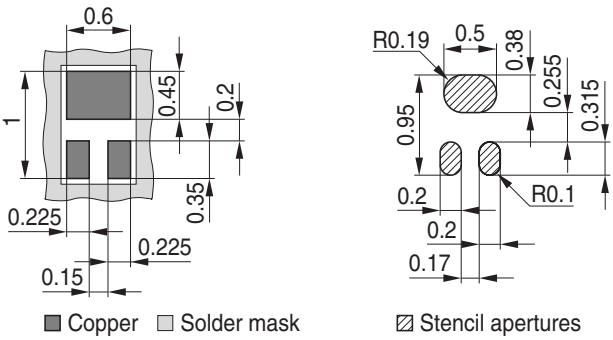
Package Outline



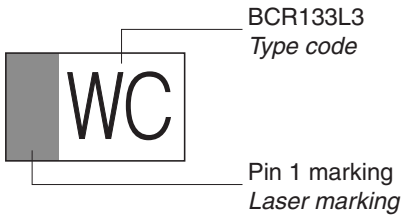
1) Dimension applies to plated terminal

Foot Print

For board assembly information please refer to Infineon website "Packages"

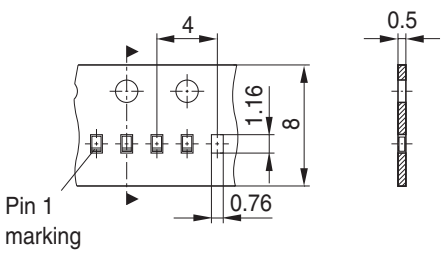


Marking Layout



Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



Edition 2006-02-01
Published by
Infineon Technologies AG
81726 München, Germany

Attention please!

The information given in this dokument shall in no event be regarded as a guarantee of conditions or characteristics (“Beschaffenheitsgarantie”). With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.

Information

For further information on technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies Office (**www.infineon.com**).

Warnings

Due to technical requirements components may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies Office.
Infineon Technologies Components may only be used in life-support devices or systems with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system, or to affect the safety or effectiveness of that device or system.
Life support devices or systems are intended to be implanted in the human body, or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.